

Fig. 1

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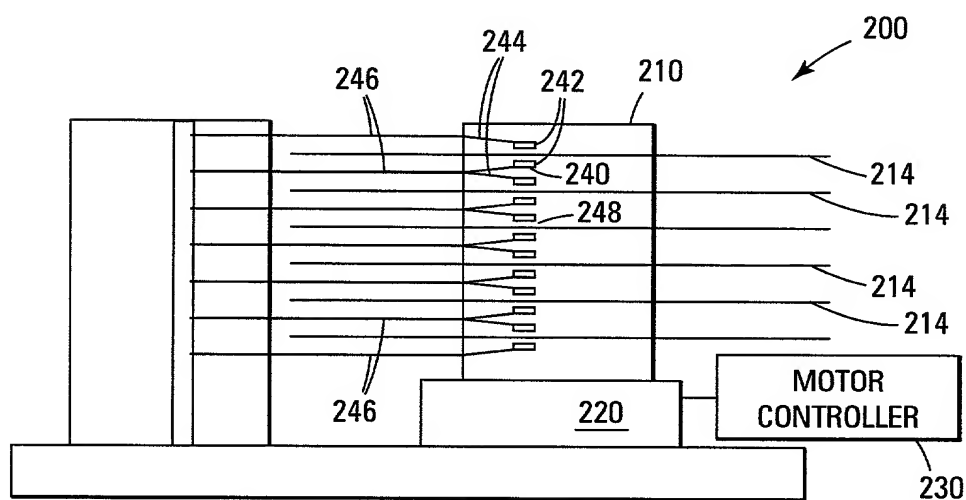


Fig. 2

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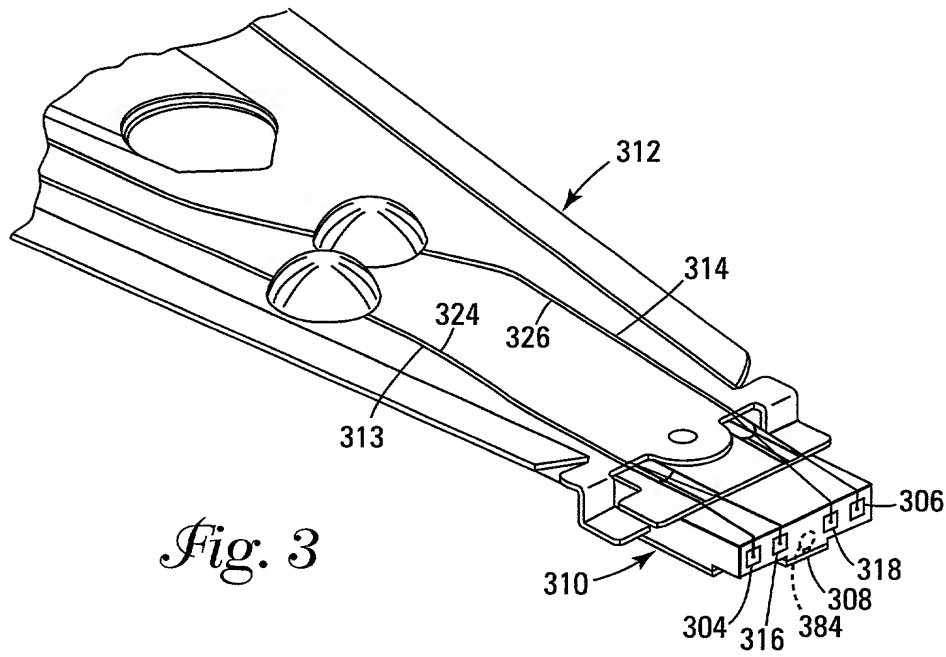


Fig. 3

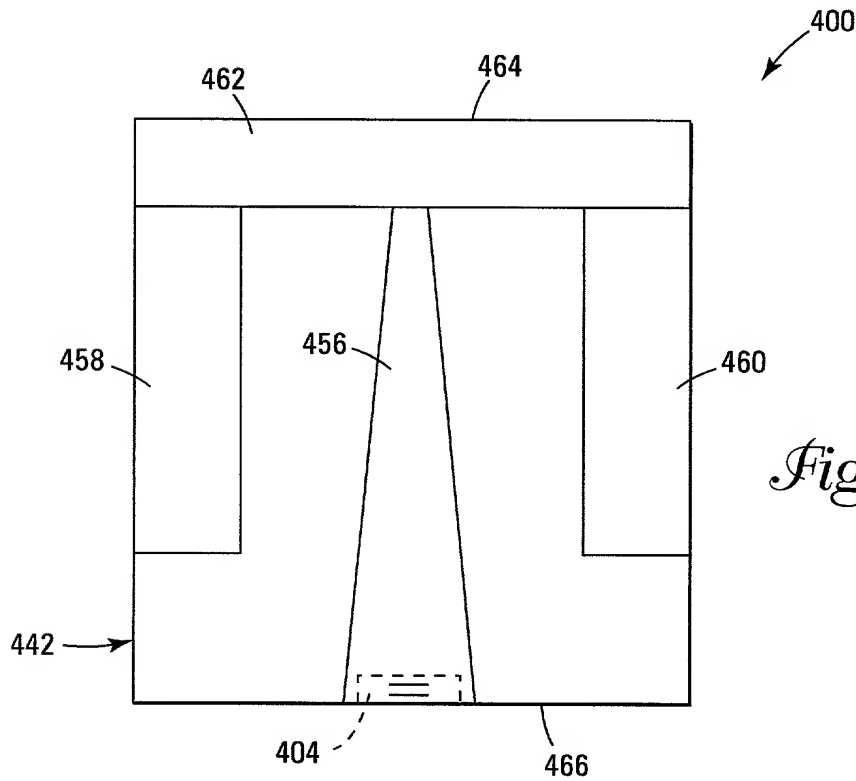
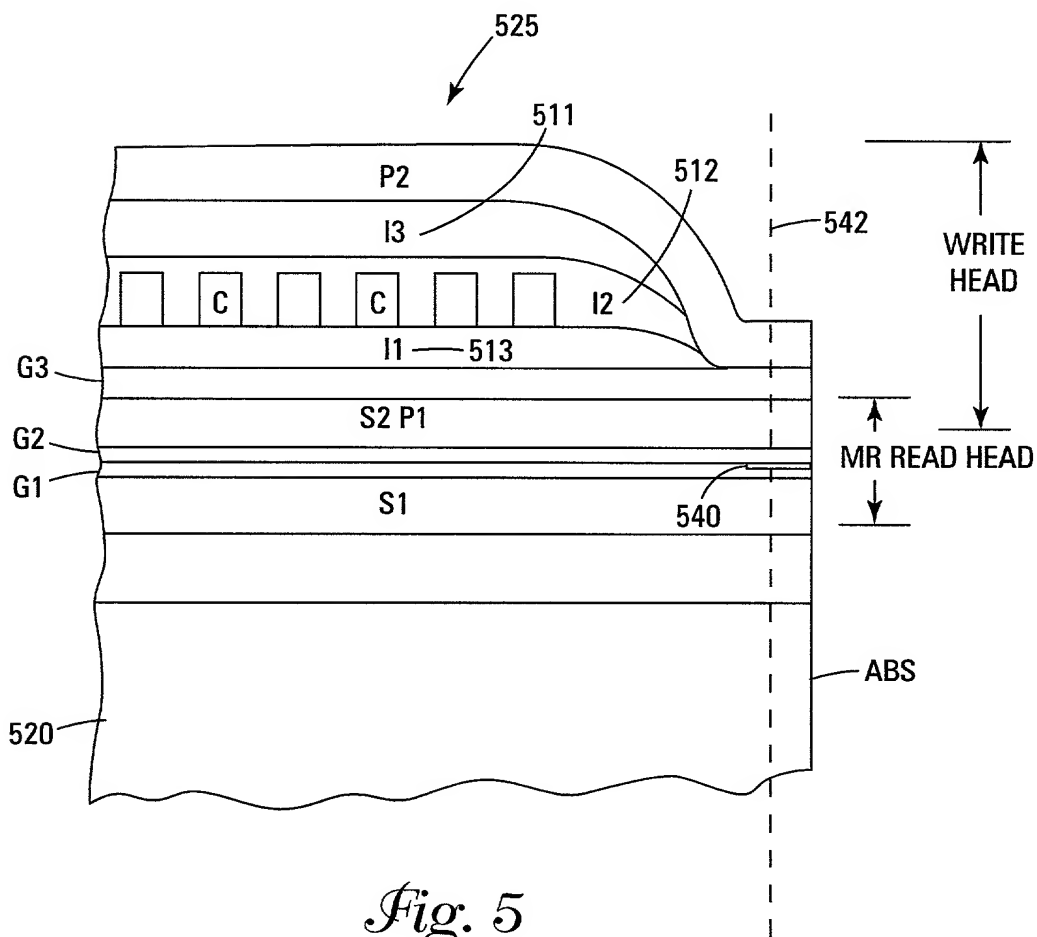


Fig. 4

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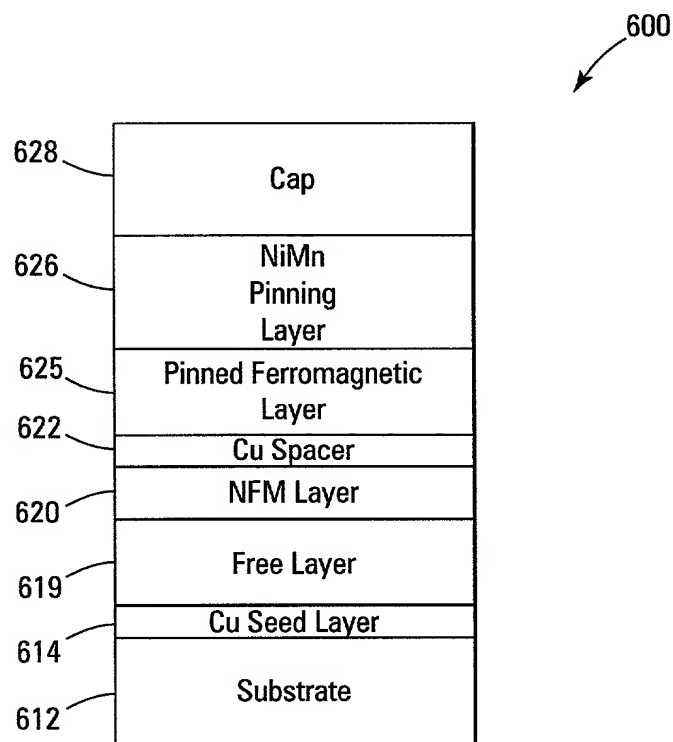


Fig. 6

	As-deposited free layer		Annealed free layer at 250°, 5 hrs	
	λ_i	λ_b	λ_i	λ_b
Without oxidation	$6 \times 10^{-5} \text{ \AA}$	$-3.2 \times 10^{-6} \text{ \AA}$	$8 \times 10^{-5} \text{ \AA}$	$-0.9 \times 10^{-6} \text{ \AA}$
With Cu seed and spacer oxidation	$4 \times 10^{-5} \text{ \AA}$	$-3.1 \times 10^{-6} \text{ \AA}$	$4 \times 10^{-5} \text{ \AA}$	$-1.5 \times 10^{-5} \text{ \AA}$

Fig. 7

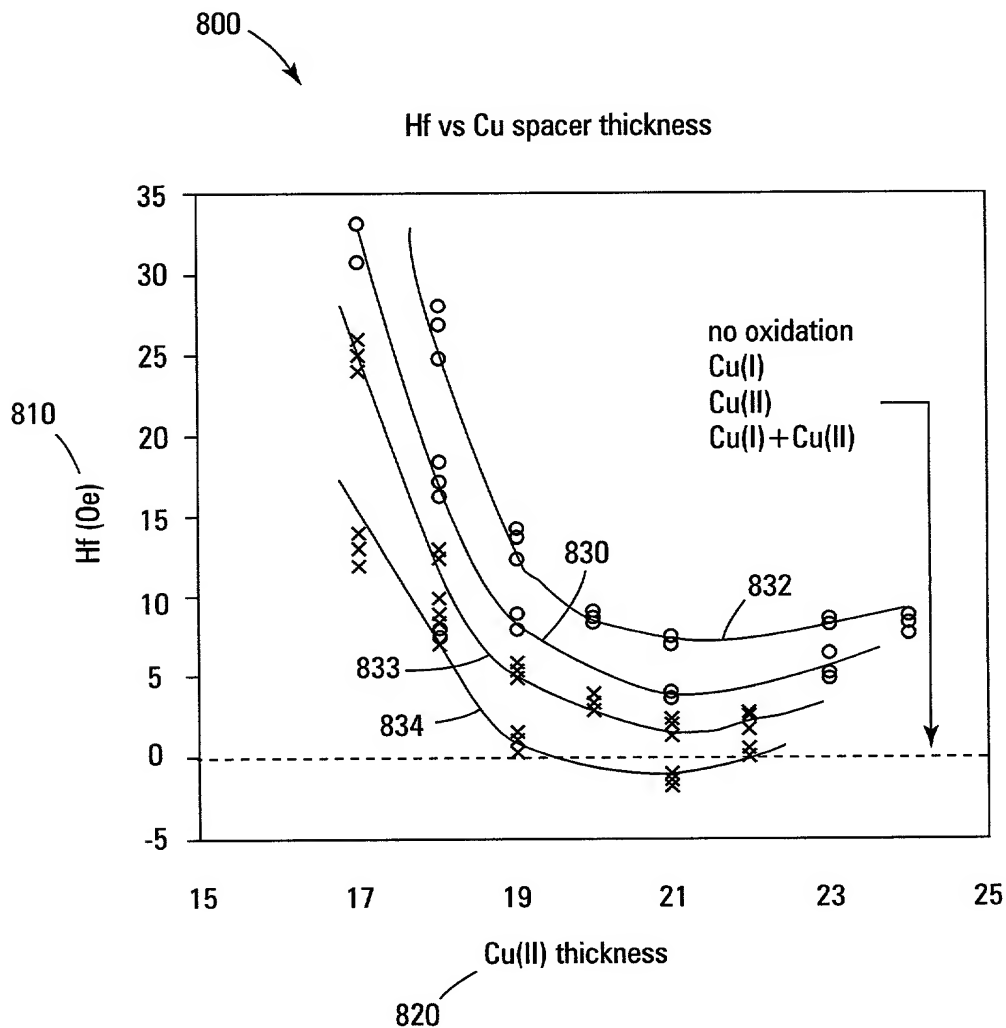


Fig. 8

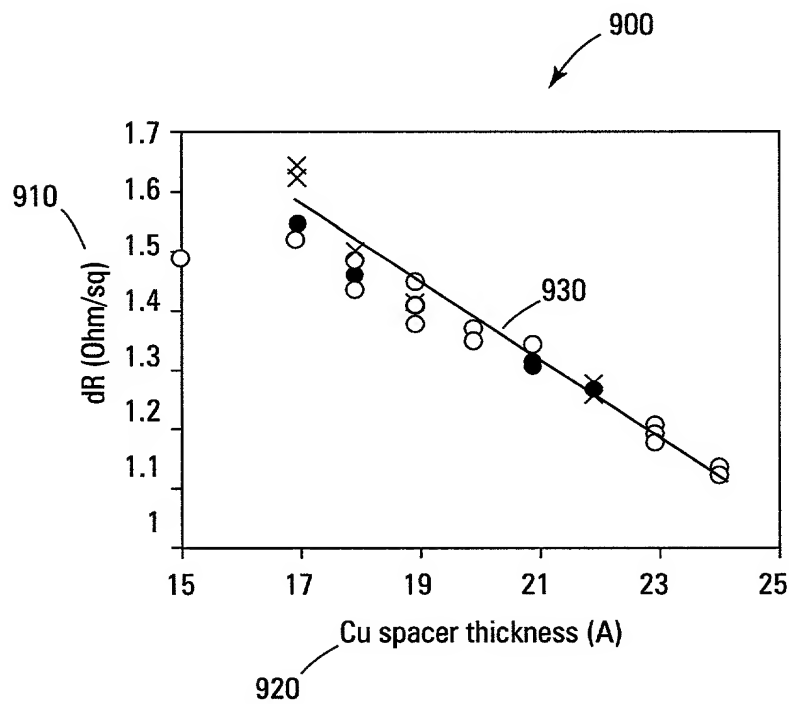


Fig. 9

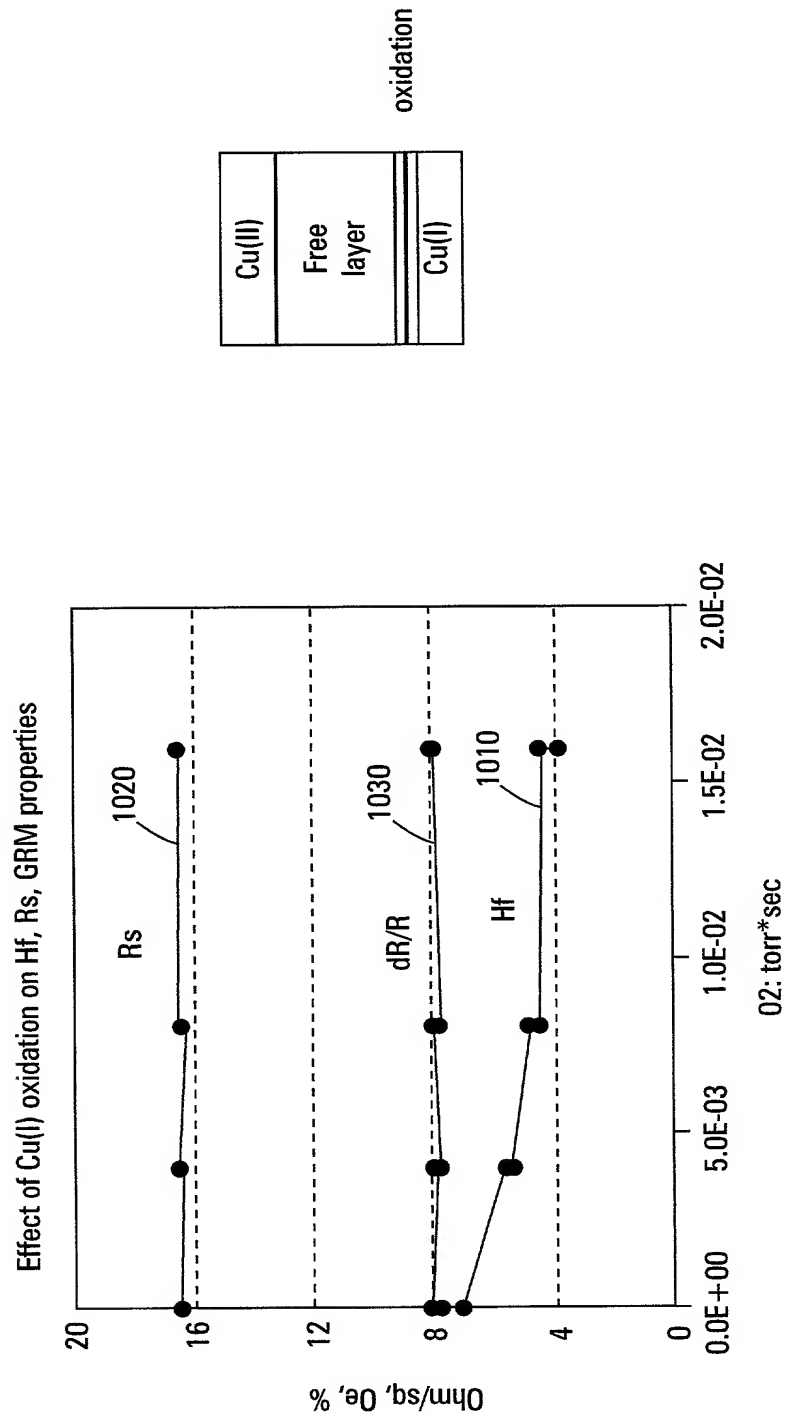


Fig. 10

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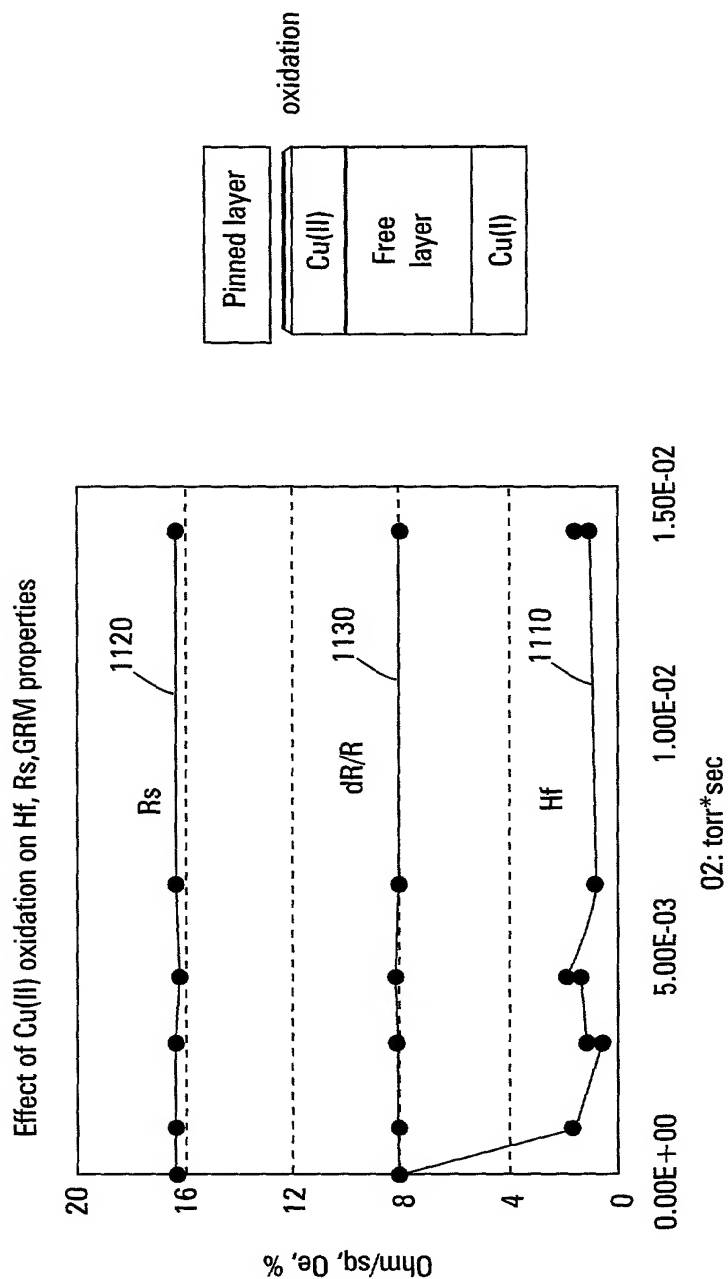


Fig. 11

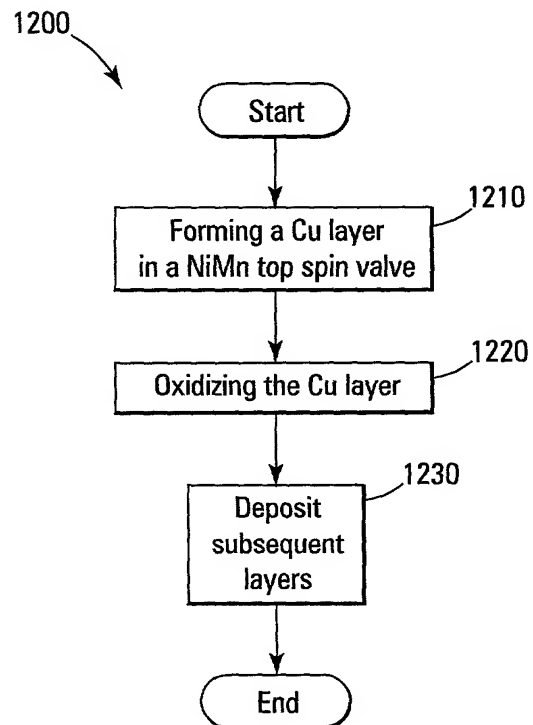


Fig. 12